

Click here for the 3D model.

| Dimensions |  |
| :--- | :--- |
| Chip Size | 0603 |
| L | $1.6 \mathrm{~mm}+/-0.1 \mathrm{~mm}$ |
| W | $0.8 \mathrm{~mm}+/-0.1 \mathrm{~mm}$ |
| T | $0.8 \mathrm{~mm}+/-0.07 \mathrm{~mm}$ |
| B | $0.4 \mathrm{~mm}+/-0.15 \mathrm{~mm}$ |
|  |  |
| Packaging Specifications | T\&R, 180 mm, Plastic Tape |
| Packaging | 4000 |
| Packaging Quantity |  |


| General Information |  |
| :--- | :--- |
| Series | CBR-SMD RF COG |
| Style | SMD Chip |
| Description | SMD, Fixed, RF, Ultra High Q, Low ESR, Class I |
| Features | Ultra High Q, Low ESR, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 5.6 mg |
| Notes | Solder Wave or Solder Reflow. |
| Shelf Life | 78 Weeks |
| MSL | 1 |


| Specifications | 9 pF |
| :--- | :--- |
| Capacitance | $+/-0.1 \mathrm{pF}$ |
| Capacitance Tolerance | 50 VDC |
| Voltage DC | 125 VDC |
| Dielectric Withstanding Voltage | $-55 /+125^{\circ} \mathrm{C}$ |
| Temperature Range | COG |
| Temperature Coefficient | $0.172 \%$ |
| Dissipation Factor | $0 \%$ Loss/Decade Hour |
| Aging Rate | 10 GOhms |
| Insulation Resistance | 580 |
| Quality Factor |  |

